SCAS101 - D3420, FEBRUARY 1990 - REVISED APRIL 1993

- Contains Eight D-Type Flip-Flops
- Clock Enable Latched to Avoid False Clocking
- Applications Include: Buffer/Storage Registers, Shift Registers, Pattern Generators
- Flow-Through Architecture Optimizes
   PCB Layout
- Center-Pin V<sub>CC</sub> and GND Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small Outline Packages and Standard Plastic 300-mil DIPs

(TOP VIEW)									
1Q [	1	U	24	CLKEN					
2Q [	2		23	[] 1D					
3Q [	3		22	] 2D					
4Q [	4		21	] 3D					
GND [	5		20	] 4D					
GND [	6		19	] v <sub>cc</sub>					
GND [	7		18	v <sub>cc</sub>					
GND [	8		17	] 5D					
5Q [	9		16	] 6D					
6Q [	10		15	] 7D					
7Q [	11		14	] 8D					
8Q [	12		13	CLK					

**DW OR NT PACKAGE** 

#### description

These circuits are positive-edge-triggered D-type flip-flops with a clock enable input.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if CLKEN is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the CLKEN input.

The 74AC11377 is characterized for operation from - 40°C to 85°C.

FUNCTION TABLE (each flip-flop)

, , , , ,									
IN	IPUTS	OUTPUT							
CLKEN	CLK	D	Q						
Н	Χ	Χ	Q <sub>0</sub>						
L	$\uparrow$	Н	Н						
L	$\uparrow$	L	L						
Х	L	Χ	$Q_0$						

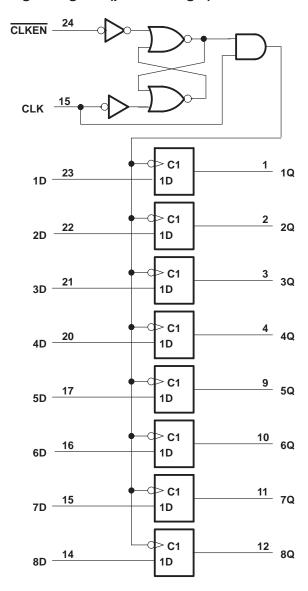
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### logic symbol<sup>†</sup>

CLKEN	24 13 23	G1 > 1C2	1	
1D		2D		1Q
2D	22		2	2Q
3D	21		3	3Q
	20		4	
4D	17		9	4Q
5D		-		5Q
6D	16		10	6Q
	15		11	
7D	14		12	7Q
8D			12	8Q

<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	– 0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	– 0.5 V to $V_{CC}$ + 0.5 V
Output voltage range, V <sub>O</sub> (see Note 1)	– 0.5 V to $V_{CC}$ + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ )	± 20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	± 50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	± 50 mA
Continuous current through V <sub>CC</sub> or GND	± 200 mA
Storage temperature range	– 65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.



### recommended operating conditions

			MIN	NOM	MAX	UNIT	
VCC	Supply voltage		3	5	5.5	V	
		V <sub>CC</sub> = 3 V	2.1				
$V_{IH}$	High-level input voltage	$V_{CC} = 4.5 V$	3.15			V	
		$V_{CC} = 5.5 \text{ V}$	3.85				
		V <sub>CC</sub> = 3 V			0.9		
VIL	Low-level input voltage $ \frac{\text{V}_{CC} = 4.5 \text{ V}}{\text{V}_{CC} = 5.5 \text{ V}} $ Input voltage				1.35	V	
					1.65		
$V_{I}$	Input voltage		0		VCC	V	
٧o	Output voltage		0		VCC	V	
		V <sub>CC</sub> = 3 V			- 4		
loh	High-level output current	$V_{CC} = 4.5 \text{ V}$			- 24	mA	
		$V_{CC} = 5.5 \text{ V}$			-24		
		V <sub>CC</sub> = 3 V			12		
loL	Low-level output current	V <sub>CC</sub> = 4.5 V			24	mA	
-		$V_{CC} = 5.5 \text{ V}$			24		
$\Delta t/\Delta v$	Input transition rise or fall rate		0		10	ns/V	
TA	Operating free-air temperature		- 40		85	°C	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	V	T,	<b>Վ = 25°C</b>	;	MINI	MAY	LINUT
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		
	I <sub>OH</sub> = -50 μA		4.4			4.4		
			5.4			5.4		
Vон	I <sub>OH</sub> = - 4 mA	3 V	2.58			2.48		V
	1 24 mA	4.5 V	3.94			3.8		
	I <sub>OH</sub> = -24 mA		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	ΙΟL = 50 μΑ	3 V			0.1		0.1	
		4.5 V			0.1		0.1	
					0.1		0.1	
$V_{OL}$	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44	V
	04 = 0	4.5 V			0.36		0.44	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
II	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			± 0.1		± 1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	5 V		4				pF

<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

## timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 2	25°C	BAIN! BAAY			
			MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	60	0	60	MHz	
	Dulas direction	CLK high	5		5			
t <sub>W</sub> Pulse duration	Pulse duration	CLK low	5		5		ns	
		Data high	6		6			
١.	Outers the shafes OLKA	Data low	5		5			
t <sub>su</sub>	Setup time before CLK↑	CLKEN high	9		9		ns	
		CLKEN low	9		9			
th	Hold time after CLK↑	CLKEN inactive or active, data	0		0		ns	

# timing requirements over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

			T <sub>A</sub> = 2	25°C	MINI MAY			
			MIN	MAX	MIN	MAX	UNIT	
fclock	Clock frequency		0	100	0	100	MHz	
	Dulan disselfers	CLK high	5		5			
t <sub>w</sub>	Pulse duration	CLK low	5		5		ns	
		Data high or low	4		4			
t <sub>su</sub>	Setup time before CLK↑	CLKEN high	6		6		ns	
		CLKEN low	6		6			
t <sub>h</sub>	Hold time after CLK↑	CLKEN inactive or active, data	0		0		ns	

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	ТО	T,	ղ = 25°C	;	B. ALINI	BA A V	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
fmax			60			60		MHz
t <sub>PLH</sub>	CLIV	A O	4	9.8	15.7	4	17.9	
<sup>t</sup> PHL	CLK	Any Q	4.9	11.4	18	4.9	19.9	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

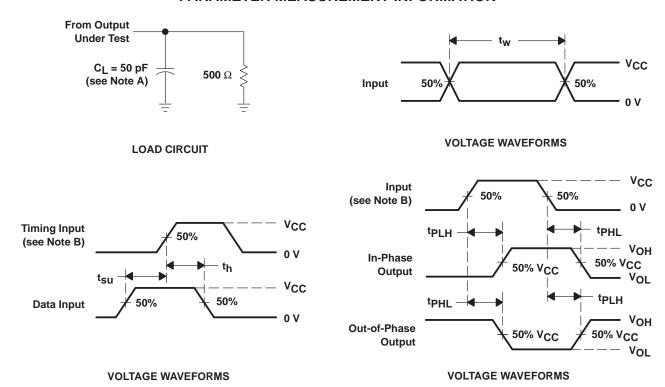
PARAMETER	FROM	ТО	T <sub>A</sub> = 25°C			MIN	MAY	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIN	MAX	UNIT
f <sub>max</sub>			100			100		MHz
<sup>t</sup> PLH	011/	A O	3.3	6.6	9.9	3.3	11.3	
<sup>t</sup> PHL	CLK	Any Q	4.1	7.8	11.5	4.1	12.9	ns

### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	72	pF



#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} = 3 \text{ ns}$ ,  $t_{f} = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74AC11377DW	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
74AC11377DWR	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
74AC11377DWR	OBSOLETE	SOIC	DW	24	TBD	Call TI	Call TI
74AC11377NT	OBSOLETE	PDIP	NT	24	TBD	Call TI	Call TI
74AC11377NT	OBSOLETE	PDIP	NT	24	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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